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PATENT

Atty. Dkt. No. AMAT/7773/PPC/CMP/RKK

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chen, et al.

Serial No.: 10/678,906

Confirmation No.: 2224

Filed: October 3, 2003

For: Method for Reducing
Delamination During
Chemical Mechanical
Polishing

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Group Art Unit: 3723

Examiner: Shantese L. McDonald

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on November 23, 2004, with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
<u>11/23/2004</u> Date	<u><i>[Signature]</i></u> Signature

Dear Sir:

RESPONSE TO OFFICE ACTION DATED AUGUST 25, 2004

In response to the Office Action dated August 25, 2004, having a shortened statutory period for response set to expire on November 25, 2004, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/7773/BKH, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Specification begin on page 2 of this paper. **Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper. **Remarks** begin on page 9 of this paper.